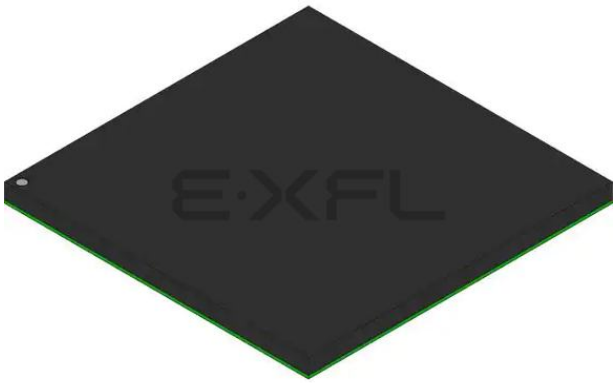

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	PowerPC e300
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	533MHz
Co-Processors/DSP	Security; SEC
RAM Controllers	DDR, DDR2
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100/1000Mbps (2)
SATA	-
USB	USB 2.0 + PHY (2)
Voltage - I/O	1.8V, 2.5V, 3.3V
Operating Temperature	0°C ~ 105°C (TA)
Security Features	Cryptography, Random Number Generator
Package / Case	672-LBGA
Supplier Device Package	672-TBGA (35x35)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc8349ezuajdb

  - Complies with USB specification Rev. 2.0
  - Can operate as a stand-alone USB device
    - One upstream facing port
    - Six programmable USB endpoints
  - Can operate as a stand-alone USB host controller
    - USB root hub with one downstream-facing port
    - Enhanced host controller interface (EHCI) compatible
    - High-speed (480 Mbps), full-speed (12 Mbps), and low-speed (1.5 Mbps) operations
  - External PHY with UTMI, serial and UTMI+ low-pin interface (ULPI)
- Universal serial bus (USB) multi-port host controller
  - Can operate as a stand-alone USB host controller
    - USB root hub with one or two downstream-facing ports
    - Enhanced host controller interface (EHCI) compatible
    - Complies with *USB Specification Rev. 2.0*
  - High-speed (480 Mbps), full-speed (12 Mbps), and low-speed (1.5 Mbps) operations
  - Direct connection to a high-speed device without an external hub
  - External PHY with serial and low-pin count (ULPI) interfaces
- Local bus controller (LBC)
  - Multiplexed 32-bit address and data operating at up to 133 MHz
  - Eight chip selects for eight external slaves
  - Up to eight-beat burst transfers
  - 32-, 16-, and 8-bit port sizes controlled by an on-chip memory controller
  - Three protocol engines on a per chip select basis:
    - General-purpose chip select machine (GPCM)
    - Three user-programmable machines (UPMs)
    - Dedicated single data rate SDRAM controller
  - Parity support
  - Default boot ROM chip select with configurable bus width (8-, 16-, or 32-bit)
- Programmable interrupt controller (PIC)
  - Functional and programming compatibility with the MPC8260 interrupt controller
  - Support for 8 external and 35 internal discrete interrupt sources
  - Support for 1 external (optional) and 7 internal machine checkstop interrupt sources
  - Programmable highest priority request
  - Four groups of interrupts with programmable priority
  - External and internal interrupts directed to host processor
  - Redirects interrupts to external $\overline{\text{INTA}}$ pin in core disable mode.
  - Unique vector number for each interrupt source

Figure 3 shows the undershoot and overshoot voltage of the PCI interface of the MPC8349EA for the 3.3-V signals, respectively.

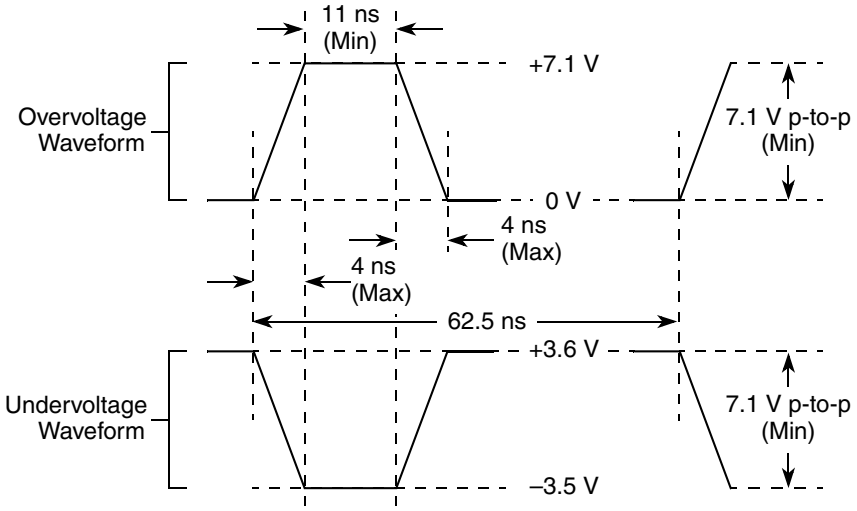


Figure 3. Maximum AC Waveforms on PCI Interface for 3.3-V Signaling

2.1.3 Output Driver Characteristics

Table 3 provides information on the characteristics of the output driver strengths. The values are preliminary estimates.

Table 3. Output Drive Capability

Driver Type	Output Impedance (Ω)	Supply Voltage
Local bus interface utilities signals	40	OV_{DD} = 3.3 V
PCI signals (not including PCI output clocks)	25	
PCI output clocks (including PCI_SYNC_OUT)	40	
DDR signal	18	GV_{DD} = 2.5 V
DDR2 signal	18 36 (half-strength mode)	GV_{DD} = 1.8 V
TSEC/10/100 signals	40	LV_{DD} = 2.5/3.3 V
DUART, system control, I^2C, JTAG, USB	40	OV_{DD} = 3.3 V
GPIO signals	40	OV_{DD} = 3.3 V, LV_{DD} = 2.5/3.3 V

2.2 Power Sequencing

This section details the power sequencing considerations for the MPC8349EA.

2.2.1 Power-Up Sequencing

MPC8349EA does not require the core supply voltage (V_{DD} and AV_{DD}) and I/O supply voltages (GV_{DD}, LV_{DD}, and OV_{DD}) to be applied in any particular order. During the power ramp up, before the power

Table 11 lists the PLL and DLL lock times.

Table 11. PLL and DLL Lock Times

Parameter/Condition	Min	Max	Unit	Notes
PLL lock times	—	100	μs	—
DLL lock times	7680	122,880	csb_clk cycles	1, 2

Notes:
1. DLL lock times are a function of the ratio between the output clock and the coherency system bus clock (csb_clk). A 2:1 ratio results in the minimum and an 8:1 ratio results in the maximum.
2. The csb_clk is determined by the CLKIN and system PLL ratio. See Section 19, "Clocking."

6 DDR and DDR2 SDRAM

This section describes the DC and AC electrical specifications for the DDR SDRAM interface of the MPC8349EA. Note that DDR SDRAM is GV_{DD}(typ) = 2.5 V and DDR2 SDRAM is GV_{DD}(typ) = 1.8 V. The AC electrical specifications are the same for DDR and DRR2 SDRAM.

NOTE

The information in this document is accurate for revision 3.0 silicon and later. For information on revision 1.1 silicon and earlier versions see the *MPC8349E PowerQUICC II Pro Integrated Host Processor Hardware Specifications*. See Section 22.1, "Part Numbers Fully Addressed by This Document," for silicon revision level determination.

6.1 DDR and DDR2 SDRAM DC Electrical Characteristics

Table 12 provides the recommended operating conditions for the DDR2 SDRAM component(s) of the MPC8349EA when GV_{DD}(typ) = 1.8 V.

Table 12. DDR2 SDRAM DC Electrical Characteristics for GV_{DD}(typ) = 1.8 V

Parameter/Condition	Symbol	Min	Max	Unit	Notes
I/O supply voltage	GV_{DD}	1.71	1.89	V	1
I/O reference voltage	MV_{REF}	0.49 × GV_{DD}	0.51 × GV_{DD}	V	2
I/O termination voltage	V_{TT}	MV_{REF} – 0.04	MV_{REF} + 0.04	V	3
Input high voltage	V_{IH}	MV_{REF} + 0.125	GV_{DD} + 0.3	V	—
Input low voltage	V_{IL}	–0.3	MV_{REF} – 0.125	V	—
Output leakage current	I_{OZ}	–9.9	9.9	μA	4
Output high current (V_{OUT} = 1.420 V)	I_{OH}	–13.4	—	mA	—

8.1.1 TSEC DC Electrical Characteristics

GMII, MII, TBI, RGMII, and RTBI drivers and receivers comply with the DC parametric attributes specified in Table 23 and Table 24. The RGMII and RTBI signals in Table 24 are based on a 2.5-V CMOS interface voltage as defined by JEDEC EIA/JESD8-5.

Table 23. GMII/TBI and MII DC Electrical Characteristics

Parameter	Symbol	Conditions		Min	Max	Unit
Supply voltage 3.3 V	LV_{DD}[2]	—		2.97	3.63	V
Output high voltage	V_{OH}	I_{OH} = –4.0 mA	LV_{DD} = Min	2.40	LV_{DD} + 0.3	V
Output low voltage	V_{OL}	I_{OL} = 4.0 mA	LV_{DD} = Min	GND	0.50	V
Input high voltage	V_{IH}	—	—	2.0	LV_{DD} + 0.3	V
Input low voltage	V_{IL}	—	—	–0.3	0.90	V
Input high current	I_{IH}	V_{IN}[1] = LV_{DD}		—	40	μA
Input low current	I_{IL}	V_{IN}[1] = GND		–600	—	μA

Notes:
1. The symbol V_{IN}, in this case, represents the LV_{IN} symbol referenced in Table 1 and Table 2.
2. GMII/MII pins not needed for RGMII or RTBI operation are powered by the OV_{DD} supply.

Table 24. RGMII/RTBI (When Operating at 2.5 V) DC Electrical Characteristics

Parameters	Symbol	Conditions		Min	Max	Unit
Supply voltage 2.5 V	LV_{DD}	—		2.37	2.63	V
Output high voltage	V_{OH}	I_{OH} = –1.0 mA	LV_{DD} = Min	2.00	LV_{DD} + 0.3	V
Output low voltage	V_{OL}	I_{OL} = 1.0 mA	LV_{DD} = Min	GND – 0.3	0.40	V
Input high voltage	V_{IH}	—	LV_{DD} = Min	1.7	LV_{DD} + 0.3	V
Input low voltage	V_{IL}	—	LV_{DD} = Min	–0.3	0.70	V
Input high current	I_{IH}	V_{IN}[1] = LV_{DD}		—	10	μA
Input low current	I_{IL}	V_{IN}[1] = GND		–15	—	μA

Note:
1. The symbol V_{IN}, in this case, represents the LV_{IN} symbol referenced in Table 1 and Table 2.

8.2 GMII, MII, TBI, RGMII, and RTBI AC Timing Specifications

The AC timing specifications for GMII, MII, TBI, RGMII, and RTBI are presented in this section.

8.2.1 GMII Timing Specifications

This section describes the GMII transmit and receive AC timing specifications.

9 USB

This section provides the AC and DC electrical specifications for the USB interface of the MPC8349EA.

9.1 USB DC Electrical Characteristics

Table 35 provides the DC electrical characteristics for the USB interface.

Table 35. USB DC Electrical Characteristics

Parameter	Symbol	Min	Max	Unit
High-level input voltage	V_{IH}	2	OV_{DD} + 0.3	V
Low-level input voltage	V_{IL}	–0.3	0.8	V
Input current	I_{IN}	—	±5	μA
High-level output voltage, I_{OH} = –100 μA	V_{OH}	OV_{DD} – 0.2	—	V
Low-level output voltage, I_{OL} = 100 μA	V_{OL}	—	0.2	V

9.2 USB AC Electrical Specifications

Table 36 describes the general timing parameters of the USB interface of the MPC8349EA.

Table 36. USB General Timing Parameters (ULPI Mode Only)

Parameter	Symbol[1]	Min	Max	Unit	Notes
USB clock cycle time	t_{USCK}	15	—	ns	2–5
Input setup to USB clock—all inputs	t_{USIVKH}	4	—	ns	2–5
Input hold to USB clock—all inputs	t_{USIXKH}	1	—	ns	2–5
USB clock to output valid—all outputs	t_{USKHOV}	—	7	ns	2–5
Output hold from USB clock—all outputs	t_{USKHOX}	2	—	ns	2–5

Notes:

1. The symbols for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{USIXKH} symbolizes USB timing (US) for the input (I) to go invalid (X) with respect to the time the USB clock reference (K) goes high (H). Also, t_{USKHOX} symbolizes USB timing (US) for the USB clock reference (K) to go high (H), with respect to the output (O) going invalid (X) or output hold time.
2. All timings are in reference to USB clock.
3. All signals are measured from $OV_{DD}/2$ of the rising edge of the USB clock to 0.4 × OV_{DD} of the signal in question for 3.3 V signaling levels.
4. Input timings are measured at the pin.
5. For active/float timing measurements, the Hi-Z or off-state is defined to be when the total current delivered through the component pin is less than or equal to that of the leakage current specification.

Table 39. Local Bus General Timing Parameters—DLL Bypass[9]

Parameter	Symbol[1]	Min	Max	Unit	Notes
Local bus cycle time	t_{LBK}	15	—	ns	2
Input setup to local bus clock	t_{LBIVKH}	7	—	ns	3, 4
Input hold from local bus clock	t_{LBIXKH}	1.0	—	ns	3, 4
LALE output fall to LAD output transition (LATCH hold time)	$t_{LBOTOT1}$	1.5	—	ns	5
LALE output fall to LAD output transition (LATCH hold time)	$t_{LBOTOT2}$	3	—	ns	6
LALE output fall to LAD output transition (LATCH hold time)	$t_{LBOTOT3}$	2.5	—	ns	7
Local bus clock to output valid	t_{LBKLOV}	—	3	ns	3
Local bus clock to output high impedance for LAD/LDP	t_{LBKHOZ}	—	4	ns	8

Notes:

1. The symbols for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, $t_{LBIXKH1}$ symbolizes local bus timing (LB) for the input (I) to go invalid (X) with respect to the time the t_{LBK} clock reference (K) goes high (H), in this case for clock one (1). Also, t_{LBKHOX} symbolizes local bus timing (LB) for the t_{LBK} clock reference (K) to go high (H), with respect to the output (O) going invalid (X) or output hold time.
2. All timings are in reference to the falling edge of LCLK0 (for all outputs and for $\overline{\text{LGTA}}$ and LUPWAIT inputs) or the rising edge of LCLK0 (for all other inputs).
3. All signals are measured from $OV_{DD}/2$ of the rising/falling edge of LCLK0 to $0.4 \times OV_{DD}$ of the signal in question for 3.3 V signaling levels.
4. Input timings are measured at the pin.
5. $t_{LBOTOT1}$ should be used when RCWH[LALE] is set and when the load on the LALE output pin is at least 10 pF less than the load on the LAD output pins.
6. $t_{LBOTOT2}$ should be used when RCWH[LALE] is not set and when the load on the LALE output pin is at least 10 pF less than the load on the LAD output pins.the
7. $t_{LBOTOT3}$ should be used when RCWH[LALE] is not set and when the load on the LALE output pin equals to the load on the LAD output pins.
8. For purposes of active/float timing measurements, the Hi-Z or off-state is defined to be when the total current delivered through the component pin is less than or equal to the leakage current specification.
9. DLL bypass mode is not recommended for use at frequencies above 66 MHz.

Figure 20 provides the AC test load for the local bus.

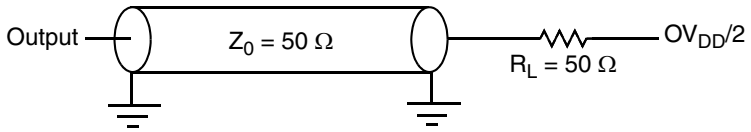


Figure 20. Local Bus C Test Load

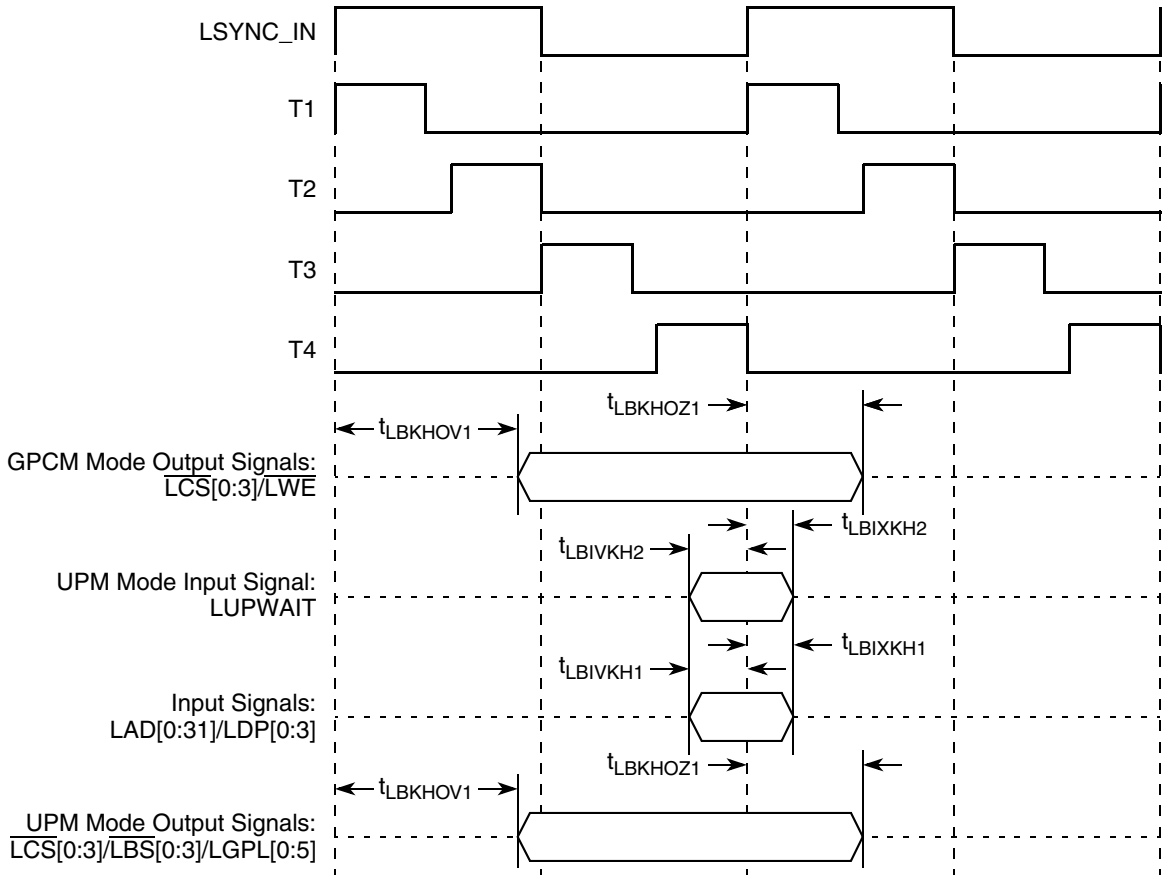


Figure 26. Local Bus Signals, GPCM/UPM Signals for LCCR[CLKDIV] = 4 (DLL Enabled)

11 JTAG

This section describes the DC and AC electrical specifications for the IEEE Std. 1149.1 (JTAG) interface of the MPC8349EA.

11.1 JTAG DC Electrical Characteristics

Table 40 provides the DC electrical characteristics for the IEEE Std. 1149.1 (JTAG) interface of the MPC8349EA.

Table 40. JTAG Interface DC Electrical Characteristics

Parameter	Symbol	Condition	Min	Max	Unit
Input high voltage	V_{IH}	—	OV_{DD} – 0.3	OV_{DD} + 0.3	V
Input low voltage	V_{IL}	—	–0.3	0.8	V
Input current	I_{IN}	—	—	±5	μA
Output high voltage	V_{OH}	I_{OH} = –8.0 mA	2.4	—	V

Table 43. I²C AC Electrical Specifications (continued)

Parameter	Symbol[1]	Min	Max	Unit
Fall time of both SDA and SCL signals[5]	t_{I2CF}	—	300	ns
Setup time for STOP condition	t_{I2PVKH}	0.6	—	μs
Bus free time between a STOP and START condition	t_{I2KHDX}	1.3	—	μs
Noise margin at the LOW level for each connected device (including hysteresis)	V_{NL}	$0.1 \times OV_{DD}$	—	V
Noise margin at the HIGH level for each connected device (including hysteresis)	V_{NH}	$0.2 \times OV_{DD}$	—	V

Notes:

1. The symbols for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{I2DVKH} symbolizes I²C timing (I2) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{I2C} clock reference (K) going to the high (H) state or setup time. Also, t_{I2SXKL} symbolizes I²C timing (I2) for the time that the data with respect to the start condition (S) goes invalid (X) relative to the t_{I2C} clock reference (K) going to the low (L) state or hold time. Also, t_{I2PVKH} symbolizes I²C timing (I2) for the time that the data with respect to the stop condition (P) reaches the valid state (V) relative to the t_{I2C} clock reference (K) going to the high (H) state or setup time. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).
2. The device provides a hold time of at least 300 ns for the SDA signal (referred to the V_{IH}(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.
3. The maximum t_{I2DVKH} must be met only if the device does not stretch the LOW period (t_{I2CL}) of the SCL signal.
4. C_B = capacitance of one bus line in pF.
5.)The device does not follow the “I2C-BUS Specifications” version 2.1 regarding the t_{I2CF} AC parameter.

Figure 32 provides the AC test load for the I²C.

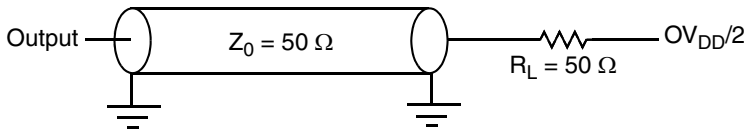


Figure 32. I²C AC Test Load

Figure 33 shows the AC timing diagram for the I²C bus.

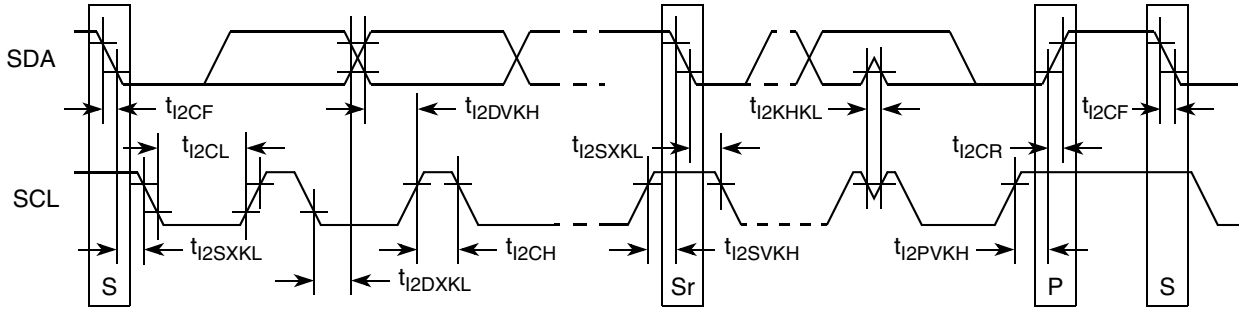


Figure 33. I²C Bus AC Timing Diagram

18.1 Package Parameters for the MPC8349EA TBGA

The package parameters are provided in the following list. The package type is 35 mm × 35 mm, 672 tape ball grid array (TBGA).

Package outline	35 mm × 35 mm
Interconnects	672
Pitch	1.00 mm
Module height (typical)	1.46 mm
Solder balls	62 Sn/36 Pb/2 Ag (ZU package) 96.5 Sn/3.5Ag (VV package)
Ball diameter (typical)	0.64 mm

18.3 Pinout Listings

Table 55 provides the pin-out listing for the MPC8349EA, 672 TBGA package.

Table 55. MPC8349EA (TBGA) Pinout Listing

Signal	Package Pin Number	Pin Type	Power Supply	Notes
PCI1 and PCI2 (One 64-Bit or Two 32-Bit)				
PCI1_INTA/IRQ_OUT	B34	O	OV_{DD}	2
PCI1_RESET_OUT	C33	O	OV_{DD}	—
PCI1_AD[31:0]	G30, G32, G34, H31, H32, H33, H34, J29, J32, J33, L30, K31, K33, K34, L33, L34, P34, R29, R30, R33, R34, T31, T32, T33, U31, U34, V31, V32, V33, V34, W33, W34	I/O	OV_{DD}	—
PCI1_C/BE[3:0]	J30, M31, P33, T34	I/O	OV_{DD}	—
PCI1_PAR	P32	I/O	OV_{DD}	—
PCI1_FRAME	M32	I/O	OV_{DD}	5
PCI1_TRDY	N29	I/O	OV_{DD}	5
PCI1_IRDY	M34	I/O	OV_{DD}	5
PCI1_STOP	N31	I/O	OV_{DD}	5
PCI1_DEVSEL	N30	I/O	OV_{DD}	5
PCI1_IDSEL	J31	I	OV_{DD}	—
PCI1_SERR	N34	I/O	OV_{DD}	5
PCI1_PERR	N33	I/O	OV_{DD}	5
PCI1_REQ[0]	D32	I/O	OV_{DD}	—
PCI1_REQ[1]/CPCI1_HS_ES	D34	I	OV_{DD}	—
PCI1_REQ[2:4]	E34, F32, G29	I	OV_{DD}	—
PCI1_GNT0	C34	I/O	OV_{DD}	—
PCI1_GNT1/CPCI1_HS_LED	D33	O	OV_{DD}	—
PCI1_GNT2/CPCI1_HS_ENUM	E33	O	OV_{DD}	—
PCI1_GNT[3:4]	F31, F33	O	OV_{DD}	—
PCI2_RESET_OUT/GPIO2[0]	W32	I/O	OV_{DD}	—
PCI2_AD[31:0]/PCI1[63:32]	AA33, AA34, AB31, AB32, AB33, AB34, AC29, AC31, AC33, AC34, AD30, AD32, AD33, AD34, AE29, AE30, AH32, AH33, AH34, AM33, AJ31, AJ32, AJ33, AJ34, AK32, AK33, AK34, AM34, AL33, AL34, AK31, AH30	I/O	OV_{DD}	—
PCI2_C/BE[3:0]/PCI1_C/BE[7:4]	AC32, AE32, AH31, AL32	I/O	OV_{DD}	—
PCI2_PAR/PCI1_PAR64	AG34	I/O	OV_{DD}	—

Table 55. MPC8349EA (TBGA) Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
MBA[2]	H4	O	GV_{DD}	—
MDIC0	AB1	I/O	—	9
MDIC1	AA1	I/O	—	9
Local Bus Controller Interface				
LAD[0:31]	AM13, AP13, AL14, AM14, AN14, AP14, AK15, AJ15, AM15, AN15, AP15, AM16, AL16, AN16, AP16, AL17, AM17, AP17, AK17, AP18, AL18, AM18, AN18, AP19, AN19, AM19, AP20, AK19, AN20, AL20, AP21, AN21	I/O	OV_{DD}	—
LDP[0]/$\overline{\text{CKSTOP\_OUT}}$	AM21	I/O	OV_{DD}	—
LDP[1]/$\overline{\text{CKSTOP\_IN}}$	AP22	I/O	OV_{DD}	—
LDP[2]/$\overline{\text{LCS}}$[4]	AN22	I/O	OV_{DD}	—
LDP[3]/$\overline{\text{LCS}}$[5]	AM22	I/O	OV_{DD}	—
LA[27:31]	AK21, AP23, AN23, AP24, AK22	O	OV_{DD}	—
$\overline{\text{LCS}}$[0:3]	AN24, AL23, AP25, AN25	O	OV_{DD}	—
$\overline{\text{LWE}}$[0:3]/LSDDQM[0:3]/$\overline{\text{LBS}}$[0:3]	AK23, AP26, AL24, AM25	O	OV_{DD}	—
LBCTL	AN26	O	OV_{DD}	—
LALE	AK24	O	OV_{DD}	—
LGPL0/LSDA10/cfg_reset_source0	AP27	I/O	OV_{DD}	—
LGPL1/$\overline{\text{LSDWE}}$/cfg_reset_source1	AL25	I/O	OV_{DD}	—
LGPL2/$\overline{\text{LSDRAS}}$/$\overline{\text{LOE}}$	AJ24	O	OV_{DD}	—
LGPL3/$\overline{\text{LSDCAS}}$/cfg_reset_source2	AN27	I/O	OV_{DD}	—
LGPL4/$\overline{\text{LGTA}}$/LUPWAIT/LPBSE	AP28	I/O	OV_{DD}	12
LGPL5/cfg_clkin_div	AL26	I/O	OV_{DD}	—
LCKE	AM27	O	OV_{DD}	—
LCLK[0:2]	AN28, AK26, AP29	O	OV_{DD}	—
LSYNC_OUT	AM12	O	OV_{DD}	—
LSYNC_IN	AJ10	I	OV_{DD}	—
General Purpose I/O Timers				
GPIO1[0]/$\overline{\text{DMA\_DREQ0}}$/GTM1_TIN1/ GTM2_TIN2	F24	I/O	OV_{DD}	—
GPIO1[1]/$\overline{\text{DMA\_DACK0}}$/ $\overline{\text{GTM1\_TGATE1}}$/$\overline{\text{GTM2\_TGATE2}}$	E24	I/O	OV_{DD}	—

Table 55. MPC8349EA (TBGA) Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
MPH1_PWRFAULT/ DR_RX_ERROR_PWRFAULT	E27	I	OV_{DD}	—
MPH1_PCTL0/DR_TX_VALID_PCTL0	A29	O	OV_{DD}	—
MPH1_PCTL1/DR_TX_VALIDH_PCTL1	D28	O	OV_{DD}	—
MPH1_CLK/DR_CLK	B29	I	OV_{DD}	—
USB Port 0				
MPH0_D0_ENABLEN/ DR_D8_CHGVBUS	C29	I/O	OV_{DD}	—
MPH0_D1_SER_TXD/ DR_D9_DCHGVBUS	A30	I/O	OV_{DD}	—
MPH0_D2_VMO_SE0/DR_D10_DPPD	E28	I/O	OV_{DD}	—
MPH0_D3_SPEED/DR_D11_DMMD	B30	I/O	OV_{DD}	—
MPH0_D4_DP/DR_D12_VBUS_VLD	C30	I/O	OV_{DD}	—
MPH0_D5_DM/DR_D13_SESS_END	A31	I/O	OV_{DD}	—
MPH0_D6_SER_RCV/DR_D14	B31	I/O	OV_{DD}	—
MPH0_D7_DRVVBUS/ DR_D15_IDPULLUP	C31	I/O	OV_{DD}	—
MPH0_NXT/DR_RX_ACTIVE_ID	B32	I	OV_{DD}	—
MPH0_DIR_DPPULLUP/DR_RESET	A32	I/O	OV_{DD}	—
MPH0_STP_SUSPEND/ DR_TX_READY	A33	I/O	OV_{DD}	—
MPH0_PWRFAULT/DR_RX_VALIDH	C32	I	OV_{DD}	—
MPH0_PCTL0/DR_LINE_STATE0	D31	I/O	OV_{DD}	—
MPH0_PCTL1/DR_LINE_STATE1	E30	I/O	OV_{DD}	—
MPH0_CLK/DR_RX_VALID	B33	I	OV_{DD}	—
Programmable Interrupt Controller				
$\overline{\text{MCP\_OUT}}$	AN33	O	OV_{DD}	2
$\overline{\text{IRQ}}$0/$\overline{\text{MCP_IN}}$/GPIO2[12]	C19	I/O	OV_{DD}	—
$\overline{\text{IRQ}}$[1:5]/GPIO2[13:17]	C22, A22, D21, C21, B21	I/O	OV_{DD}	—
$\overline{\text{IRQ}}$[6]/GPIO2[18]/$\overline{\text{CKSTOP\_OUT}}$	A21	I/O	OV_{DD}	—
$\overline{\text{IRQ}}$[7]/GPIO2[19]/$\overline{\text{CKSTOP\_IN}}$	C20	I/O	OV_{DD}	—
Ethernet Management Interface				
EC_MDC	A7	O	LV_{DD1}	—
EC_MDIO	E9	I/O	LV_{DD1}	11

Table 55. MPC8349EA (TBGA) Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
Gigabit Reference Clock				
EC_GTX_CLK125	C8	I	LV_{DD1}	—
Three-Speed Ethernet Controller (Gigabit Ethernet 1)				
TSEC1_COL/GPIO2[20]	A17	I/O	OV_{DD}	—
TSEC1_CRS/GPIO2[21]	F12	I/O	LV_{DD1}	—
TSEC1_GTX_CLK	D10	O	LV_{DD1}	3
TSEC1_RX_CLK	A11	I	LV_{DD1}	—
TSEC1_RX_DV	B11	I	LV_{DD1}	—
TSEC1_RX_ER/GPIO2[26]	B17	I/O	OV_{DD}	—
TSEC1_RXD[7:4]/GPIO2[22:25]	B16, D16, E16, F16	I/O	OV_{DD}	—
TSEC1_RXD[3:0]	E10, A8, F10, B8	I	LV_{DD1}	—
TSEC1_TX_CLK	D17	I	OV_{DD}	—
TSEC1_TXD[7:4]/GPIO2[27:30]	A15, B15, A14, B14	I/O	OV_{DD}	—
TSEC1_TXD[3:0]	A10, E11, B10, A9	O	LV_{DD1}	10
TSEC1_TX_EN	B9	O	LV_{DD1}	—
TSEC1_TX_ER/GPIO2[31]	A16	I/O	OV_{DD}	—
Three-Speed Ethernet Controller (Gigabit Ethernet 2)				
TSEC2_COL/GPIO1[21]	C14	I/O	OV_{DD}	—
TSEC2_CRS/GPIO1[22]	D6	I/O	LV_{DD2}	—
TSEC2_GTX_CLK	A4	O	LV_{DD2}	—
TSEC2_RX_CLK	B4	I	LV_{DD2}	—
TSEC2_RX_DV/GPIO1[23]	E6	I/O	LV_{DD2}	—
TSEC2_RXD[7:4]/GPIO1[26:29]	A13, B13, C13, A12	I/O	OV_{DD}	—
TSEC2_RXD[3:0]/GPIO1[13:16]	D7, A6, E8, B7	I/O	LV_{DD2}	—
TSEC2_RX_ER/GPIO1[25]	D14	I/O	OV_{DD}	—
TSEC2_TXD[7]/GPIO1[31]	B12	I/O	OV_{DD}	—
TSEC2_TXD[6]/ DR_XCVR_TERM_SEL	C12	O	OV_{DD}	—
TSEC2_TXD[5]/ DR_UTMI_OPMODE1	D12	O	OV_{DD}	—
TSEC2_TXD[4]/ DR_UTMI_OPMODE0	E12	O	OV_{DD}	—
TSEC2_TXD[3:0]/GPIO1[17:20]	B5, A5, F8, B6	I/O	LV_{DD2}	—

Table 59. CSB Frequency Options for Host Mode (continued)

CFG_CLKIN_DIV at Reset[1]	SPMF	*csb_clk* : Input Clock Ratio[2]	Input Clock Frequency (MHz)[2]			
			16.67	25	33.33	66.67
			csb_clk Frequency (MHz)			
Low	0110	6 : 1	100	150	200	
Low	0111	7 : 1	116	175	233	
Low	1000	8 : 1	133	200	266	
Low	1001	9 : 1	150	225	300	
Low	1010	10 : 1	166	250	333	
Low	1011	11 : 1	183	275		
Low	1100	12 : 1	200	300		
Low	1101	13 : 1	216	325		
Low	1110	14 : 1	233			
Low	1111	15 : 1	250			
Low	0000	16 : 1	266			
High	0010	2 : 1				133
High	0011	3 : 1			100	200
High	0100	4 : 1			133	266
High	0101	5 : 1			166	333
High	0110	6 : 1			200	
High	0111	7 : 1			233	
High	1000	8 : 1				

1 CFG_CLKIN_DIV selects the ratio between CLKIN and PCI_SYNC_OUT.
2 CLKIN is the input clock in host mode; PCI_CLK is the input clock in agent mode.

Table 60. CSB Frequency Options for Agent Mode

CFG_CLKIN_DIV at Reset[1]	SPMF	*csb_clk* : Input Clock Ratio[2]	Input Clock Frequency (MHz)[2]			
			16.67	25	33.33	66.67
			csb_clk Frequency (MHz)			
Low	0010	2 : 1				133
Low	0011	3 : 1			100	200
Low	0100	4 : 1		100	133	266
Low	0101	5 : 1		125	166	333

19.3 Suggested PLL Configurations

Table 62 shows suggested PLL configurations for 33 and 66 MHz input clocks.

Table 62. Suggested PLL Configurations

Ref No.[1]	RCWL		400 MHz Device			533 MHz Device			667 MHz Device		
	SPMF	CORE PLL	Input Clock Freq (MHz)[2]	CSB Freq (MHz)	Core Freq (MHz)	Input Clock Freq (MHz)[2]	CSB Freq (MHz)	Core Freq (MHz)	Input Clock Freq (MHz)[2]	CSB Freq (MHz)	Core Freq (MHz)
33 MHz CLKIN/PCI_CLK Options											
922	**1001**	**0100010**	—	—	—	—	—	f300	33	300	300
723	**0111**	**0100011**	33	233	350	33	233	350	33	233	350
604	**0110**	**0000100**	33	200	400	33	200	400	33	200	400
624	**0110**	**0100100**	33	200	400	33	200	400	33	200	400
803	**1000**	**0000011**	33	266	400	33	266	400	33	266	400
823	**1000**	**0100011**	33	266	400	33	266	400	33	266	400
903	**1001**	**0000011**	—			33	300	450	33	300	450
923	**1001**	**0100011**	—			33	300	450	33	300	450
704	**0111**	**0000011**	—			33	233	466	33	233	466
724	**0111**	**0100011**	—			33	233	466	33	233	466
A03	1010	0000011	—			33	333	500	33	333	500
804	**1000**	**0000100**	—			33	266	533	33	266	533
705	**0111**	**0000101**	—			—			33	233	583
606	**0110**	**0000110**	—			—			33	200	600
904	**1001**	**0000100**	—			—			33	300	600
805	**1000**	**0000101**	—			—			33	266	667
A04	**1010**	**0000100**	—			—			33	333	667
66 MHz CLKIN/PCI_CLK Options											
304	**0011**	**0000100**	66	200	400	66	200	400	66	200	400
324	**0011**	**0100100**	66	200	400	66	200	400	66	200	400
403	**0100**	**0000011**	66	266	400	66	266	400	66	266	400
423	**0100**	**0100011**	66	266	400	66	266	400	66	266	400
305	**0011**	**0000101**	—			66	200	500	66	200	500
503	0101	0000011	—			66	333	500	66	333	500
404	**0100**	**0000100**	—			66	266	533	66	266	533

Table 62. Suggested PLL Configurations (continued)

Ref No.[1]	RCWL		400 MHz Device			533 MHz Device			667 MHz Device		
	SPMF	CORE PLL	Input Clock Freq (MHz)[2]	CSB Freq (MHz)	Core Freq (MHz)	Input Clock Freq (MHz)[2]	CSB Freq (MHz)	Core Freq (MHz)	Input Clock Freq (MHz)[2]	CSB Freq (MHz)	Core Freq (MHz)
306	**0011**	**0000110**	—			—			66	200	600
405	**0100**	**0000101**	—			—			66	266	667
504	**0101**	**0000100**	—			—			66	333	667

1 The PLL configuration reference number is the hexadecimal representation of RCWL, bits 4–15 associated with the SPMF and COREPLL settings given in the table.
2 The input clock is CLKIN for PCI host mode or PCI_CLK for PCI agent mode.

20 Thermal

This section describes the thermal specifications of the MPC8349EA.

20.1 Thermal Characteristics

Table 63 provides the package thermal characteristics for the 672 35 × 35 mm TBGA of the MPC8349EA.

Table 63. Package Thermal Characteristics for TBGA

Characteristic	Symbol	Value	Unit	Notes
Junction-to-ambient natural convection on single-layer board (1s)	$R_{\theta JA}$	14	°C/W	1, 2
Junction-to-ambient natural convection on four-layer board (2s2p)	$R_{\theta JMA}$	11	°C/W	1, 3
Junction-to-ambient (at 200 ft/min) on single-layer board (1s)	$R_{\theta JMA}$	11	°C/W	1, 3
Junction-to-ambient (at 200 ft/min) on four-layer board (2s2p)	$R_{\theta JMA}$	8	°C/W	1, 3
Junction-to-ambient (at 2 m/s) on single-layer board (1s)	$R_{\theta JMA}$	9	°C/W	1, 3
Junction-to-ambient (at 2 m/s) on four-layer board (2s2p)	$R_{\theta JMA}$	7	°C/W	1, 3
Junction-to-board thermal	$R_{\theta JB}$	3.8	°C/W	4
Junction-to-case thermal	$R_{\theta JC}$	1.7	°C/W	5

Heat sink vendors include the following list:

Aavid Thermalloy 603-224-9988
80 Commercial St.
Concord, NH 03301
Internet: www.aavidthermalloy.com

Alpha Novatech 408-567-8082
473 Sapena Ct. #12
Santa Clara, CA 95054
Internet: www.alphanovatech.com

International Electronic Research Corporation (IERC) 818-842-7277
413 North Moss St.
Burbank, CA 91502
Internet: www.ctscorp.com

Millennium Electronics (MEI) 408-436-8770
Loroco Sites
671 East Brokaw Road
San Jose, CA 95112
Internet: www.mei-thermal.com

Tyco Electronics 800-522-2800
Chip Coolers™
P.O. Box 3668
Harrisburg, PA 17105-3668
Internet: www.chipcoolers.com

Wakefield Engineering 603-635-5102
33 Bridge St.
Pelham, NH 03076
Internet: www.wakefield.com

Interface material vendors include the following:

Chomerics, Inc. 781-935-4850
77 Dragon Ct.
Woburn, MA 01801
Internet: www.chomerics.com

Dow-Corning Corporation 800-248-2481
Dow-Corning Electronic Materials
P.O. Box 994
Midland, MI 48686-0997
Internet: www.dowcorning.com

Shin-Etsu MicroSi, Inc. 888-642-7674
10028 S. 51st St.
Phoenix, AZ 85044
Internet: www.microsi.com

2. The e300 core PLL generates the core clock as a slave to the platform clock. The frequency ratio between the e300 core clock and the platform clock is selected using the e300 PLL ratio configuration bits as described in Section 19.2, “Core PLL Configuration.”

21.2 PLL Power Supply Filtering

Each PLL gets power through independent power supply pins ($AV_{DD}1$, $AV_{DD}2$, respectively). The AV_{DD} level should always equal to V_{DD}, and preferably these voltages are derived directly from V_{DD} through a low frequency filter scheme.

There are a number of ways to provide power reliably to the PLLs, but the recommended solution is to provide four independent filter circuits as illustrated in Figure 42, one to each of the four AV_{DD} pins. Independent filters to each PLL reduce the opportunity to cause noise injection from one PLL to the other.

The circuit filters noise in the PLL resonant frequency range from 500 kHz to 10 MHz. It should be built with surface mount capacitors with minimum effective series inductance (ESL). Consistent with the recommendations of Dr. Howard Johnson in *High Speed Digital Design: A Handbook of Black Magic* (Prentice Hall, 1993), multiple small capacitors of equal value are recommended over a single large value capacitor.

To minimize noise coupled from nearby circuits, each circuit should be placed as closely as possible to the specific AV_{DD} pin being supplied. It should be possible to route directly from the capacitors to the AV_{DD} pin, which is on the periphery of package, without the inductance of vias.

Figure 42 shows the PLL power supply filter circuit.

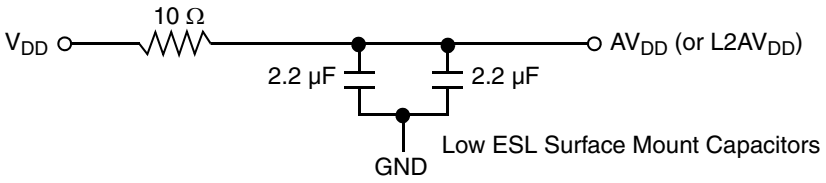


Figure 42. PLL Power Supply Filter Circuit

21.3 Decoupling Recommendations

Due to large address and data buses and high operating frequencies, the MPC8349EA can generate transient power surges and high frequency noise in its power supply, especially while driving large capacitive loads. This noise must be prevented from reaching other components in the MPC8349EA system, and the device itself requires a clean, tightly regulated source of power. Therefore, the system designer should place at least one decoupling capacitor at each V_{DD}, OV_{DD}, GV_{DD}, and LV_{DD} pin of the device. These capacitors should receive their power from separate V_{DD}, OV_{DD}, GV_{DD}, LV_{DD}, and GND power planes in the PCB, with short traces to minimize inductance. Capacitors can be placed directly under the device using a standard escape pattern. Others can surround the part.

These capacitors should have a value of 0.01 or 0.1 µF. Only ceramic SMT (surface mount technology) capacitors should be used to minimize lead inductance, preferably 0402 or 0603 sizes.

In addition, distribute several bulk storage capacitors around the PCB, feeding the V_{DD}, OV_{DD}, GV_{DD}, and LV_{DD} planes, to enable quick recharging of the smaller chip capacitors. These bulk capacitors should

have a low ESR (equivalent series resistance) rating to ensure the quick response time. They should also be connected to the power and ground planes through two vias to minimize inductance. Suggested bulk capacitors are 100–330 µF (AVX TPS tantalum or Sanyo OSCON).

21.4 Connection Recommendations

To ensure reliable operation, connect unused inputs to an appropriate signal level. Unused active low inputs should be tied to OV_{DD}, GV_{DD}, or LV_{DD} as required. Unused active high inputs should be connected to GND. All NC (no-connect) signals must remain unconnected.

Power and ground connections must be made to all external V_{DD}, GV_{DD}, LV_{DD}, OV_{DD}, and GND pins of the MPC8349EA.

21.5 Output Buffer DC Impedance

The MPC8349EA drivers are characterized over process, voltage, and temperature. For all buses, the driver is a push-pull single-ended driver type (open drain for I^2C).

To measure Z_0 for the single-ended drivers, an external resistor is connected from the chip pad to OV_{DD} or GND. Then the value of each resistor is varied until the pad voltage is $OV_{DD}/2$ (see Figure 43). The output impedance is the average of two components, the resistances of the pull-up and pull-down devices. When data is held high, SW1 is closed (SW2 is open) and R_P is trimmed until the voltage at the pad equals $OV_{DD}/2$. R_P then becomes the resistance of the pull-up devices. R_P and R_N are designed to be close to each other in value. Then, $Z_0 = (R_P + R_N) \div 2$.

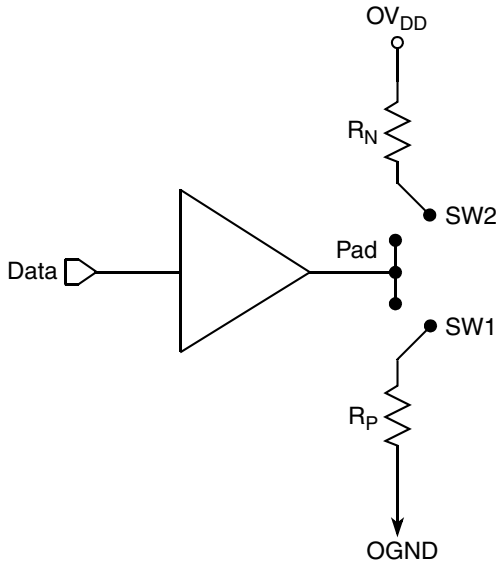
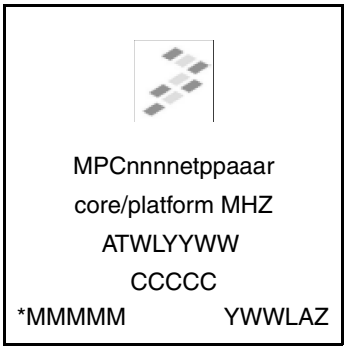


Figure 43. Driver Impedance Measurement

Two measurements give the value of this resistance and the strength of the driver current source. First, the output voltage is measured while driving logic 1 without an external differential termination resistor. The measured voltage is $V_1 = R_{source} \times I_{source}$. Second, the output voltage is measured while driving logic 1 with an external precision differential termination resistor of value R_{term}. The measured voltage is

22.2 Part Marking

Parts are marked as in the example shown in Figure 44.



Notes:
ATWLYYWW is the traceability code.
CCCCC is the country code.
MMMMM is the mask number.
YWWLAZ is the assembly traceability code.

Figure 44. Freescale Part Marking for TBGA Devices

23 Document Revision History

This table provides a revision history of this document.

Table 68. Document Revision History

Rev. Number	Date	Substantive Change(s)
13	09/2011	• In Section 2.2, "Power Sequencing," added Section 2.2.1, "Power-Up Sequencing" and Figure 4. • In Table 25, Table 29 and Table 31, removed the GTX_CLK125. • In Table 34, updated t_{MDKHDX} Max value from 170ns to 70ns.
12	11/2010	• In Table 55 added note for pin LGPL4. • In Section 21.7, "Pull-Up Resistor Requirements, updated the list of open drain type pins.
11	05/2010	• In Table 25 through Table 30, changed V_{IL}(min) to V_{IH}(max) to (20%–80%). • Added Table 8, "EC_GTX_CLK125 AC Timing Specifications."
10	5/2009	• In Table 57, updated frequency for max csb_clk to 333 MHz and DDR2, from 100-200 to 100-133 at core frequency = 533MHz. • In Section 18.1, "Package Parameters for the MPC8349EA TBGA, changed solder ball for TBGA and PBGA from 95.5 Sn/0.5 Cu/4 Ag to 96.5 Sn/3.5 Ag. • In Table 66, footnote 1, changed 667(TBGA) to 533(TBGA). footnote 4, added data rate for DDR1 and DDR2.